

# Product Change Notification - JAON-07YGZF687

**Date:** 25 May 2016

**Product Category:** Memory; RF and Security; Analog (Thermal, Power Management & Safety); Analog (Linear & Mixed Signal) AND Interface; 8-bit Microcontrollers

**Notification subject:** CCB 1833 Final Notice: Qualification of CuPdAu bond wire in selected products of the 40K, 42K, 77K, 90K, 120K, 121K, 150K, 160K and 200K wafer technologies available in 8L PDIP package at MMT site.

**Notification text:** **PCN Status:**  
Final notification

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 40K, 42K, 77K, 90K, 120K, 121K, 150K, 160K and 200K wafer technologies available in 8L PDIP package at MMT assembly site.

**Pre Change:**

Gold (Au) or Palladium coated copper wire (PdCu) bond wire

**Post Change:**

Palladium coated copper with gold flash (CuPdAu) bond wire

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	MMT assembly site	MMT assembly site
<b>Wire material</b>	Au wire or PdCu wire	CuPdAu wire
<b>Die attach material</b>	CRM-1064L	CRM-1064L
<b>Molding compound material</b>	GE800	GE800
<b>Lead frame material</b>	CDA194	CDA194

**Reason for Change:**

To improve manufacturability by qualifying Palladium coated copper with gold flash (CuPdAu) bond wire.

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**

June 1, 2016 (date code: 1622)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Summary Table:**

	January 2016				---->				May 2016				June 2016				
WW	01	02	03	04					18	19	20	21	22	23	24	25	26
Initial PCN Issue Date		X															
Qual Report Availability												X					
Final PCN Issue Date												X					
Implementation Date													X				

**Markings to Distinguish Revised from Unrevised Devices:**

Traceability code

**Revision History:**

**January 13, 2016:** Issued initial notification.

**May 25, 2016:** Issued final notification. Attached the qualification report. Revised the estimated first ship date from April 20, 2016 to June 1, 2016. Updated the summary table for the Qual Report Availability and Final PCN issue date. Updated the scope of change from selected products of the 200K wafer technology to selected products of the 40K, 42K, 77K, 90K, 120K, 121K, 150K, 160K and 200K wafer technologies available in 8L PDIP package at MMT assembly site.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

[PCN\\_JAON-07YGZF687\\_Qual\\_Report.pdf](#)

[PCN\\_JAON-07YGZF687\\_Affected\\_CPN.pdf](#)

[PCN\\_JAON-07YGZF687\\_Affected\\_CPN.xls](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_JAON-07YGZF687
CATALOG_PART_NBR
24AA00/P
24AA00-I/P
24AA02/PRVC
24AA02-I/PRVC
24AA04/P
24AA04/PRVC
24AA044-E/P
24AA044-I/P
24AA04H-I/P
24AA04-I/P
24AA04-I/PRVC
24AA08/P
24AA08H-I/P
24AA08-I/P
24AA08-I/PB25
24AA128-I/P
24AA128-I/PRVF
24AA16/P
24AA16-E/P
24AA16H-I/P
24AA16-I/P
24AA256UID-I/P
24AA32AF-I/P
24AA32A-I/P
24AA512-I/P
24AA64/P
24AA64/PRVA
24AA64-E/P
24AA64F-I/P
24AA64-I/P
24AA65/P
24C00/P
24C00-E/P
24C00-I/P
24C65/P
24C65-I/P
24FC128-I/P
24FC512-I/P
24FC64F-I/P
24FC64-I/P
24LC00/P
24LC00-I/P
24LC02B/PROCRVC
24LC02B/PRVC

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Affected Catalog Part Numbers (CPN)

PCN_JAON-07YGZF687
CATALOG_PART_NBR
24LC02B-E/PRVC
24LC02B-I/PRVC
24LC04B/P
24LC04B/PRVC
24LC04B-E/P
24LC04B-E/PRVC
24LC04BH-E/P
24LC04BH-I/P
24LC04B-I/P
24LC04B-I/PRVC
24LC08B/P
24LC08B-E/P
24LC08BH-E/P
24LC08BH-I/P
24LC08B-I/P
24LC128-E/P
24LC128-I/P
24LC128-I/PRVE
24LC128-I/PRVF
24LC16B/P
24LC16B-E/P
24LC16BH-E/P
24LC16BH-I/P
24LC16B-I/P
24LC21/P
24LC21A/P
24LC21A-I/P
24LC21-I/P
24LC22A-I/P
24LC256-I/PRVE
24LC32A/P
24LC32A-E/P
24LC32AF-E/P
24LC32AF-I/P
24LC32A-I/P
24LC32A-I/PRVE
24LC512-E/P
24LC512-I/P
24LC512-I/PRVE
24LC64-E/P
24LC64F-E/P
24LC64F-I/P
24LC64-I/P
24LC64-I/PRVE

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Affected Catalog Part Numbers (CPN)

PCN_JAON-07YGZF687
CATALOG_PART_NBR
24LC65/P
24LC65-I/P
24LCS21A/P
24LCS21A-I/P
24LCS22A-I/P
25A512-I/P
25AA010A-I/P
25AA020A-I/P
25AA040/P
25AA040A-I/P
25AA040-I/P
25AA080/P
25AA080A-I/P
25AA080B-I/P
25AA080B-I/PB79
25AA080C-I/P
25AA080D-I/P
25AA080-I/P
25AA1024-I/P
25AA128-I/P
25AA160/P
25AA160A-I/P
25AA160B-I/P
25AA160C-I/P
25AA160D-E/P
25AA160D-I/P
25AA160-I/P
25AA256-E/P
25AA256-I/P
25AA320A-I/P
25AA320-I/P
25AA512-I/P
25AA640A-E/P
25AA640A-I/P
25AA640-I/P
25C040/P
25C040-E/P
25C040-I/P
25C080/P
25C080-E/P
25C080-I/P
25C160/P
25C160-E/P
25C160-I/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-07YGZF687
CATALOG_PART_NBR
25C320/P
25C320-E/P
25C320-I/P
25LC010A-E/P
25LC010A-I/P
25LC020A-E/P
25LC020A-I/P
25LC040/P
25LC040A-E/P
25LC040A-I/P
25LC040A-M/P
25LC040-I/P
25LC080/P
25LC080A-E/P
25LC080A-I/P
25LC080B-E/P
25LC080B-I/P
25LC080C-E/P
25LC080C-I/P
25LC080D-E/P
25LC080D-I/P
25LC080-I/P
25LC1024-E/P
25LC1024-I/P
25LC128-E/P
25LC128-I/P
25LC160/P
25LC160A-E/P
25LC160A-I/P
25LC160A-I/PA79
25LC160B-E/P
25LC160B-I/P
25LC160C-E/P
25LC160C-I/P
25LC160D-E/P
25LC160D-I/P
25LC160-I/P
25LC256-E/P
25LC256-I/P
25LC320/P
25LC320A-E/P
25LC320A-I/P
25LC320-E/P
25LC320-I/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-07YGZF687
CATALOG_PART_NBR
25LC512-E/P
25LC512-I/P
25LC640A-E/P
25LC640A-I/P
25LC640-E/P
25LC640-I/P
34AA04-E/P
34AA04-I/P
93AA46/P
93AA46A-I/P
93AA46B-I/P
93AA46C-I/P
93AA56/P
93AA56A-I/P
93AA56B-I/P
93AA56C-I/P
93AA56-I/P
93AA66/P
93AA66A-I/P
93AA66B-I/P
93AA66C-I/P
93AA66-I/P
93AA76/P
93AA76A-I/P
93AA76B-I/P
93AA76C-I/P
93AA86/P
93AA86A-I/P
93AA86B-I/P
93AA86C-I/P
93C46A-E/P
93C46A-I/P
93C46B/P
93C46B/PROCRVA
93C46B/PRVA
93C46B-E/P
93C46B-E/PRVA
93C46B-I/P
93C46B-I/PRVA
93C46C-E/P
93C46C-I/P
93C56A-E/P
93C56A-I/P
93C56B-E/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-07YGZF687
CATALOG_PART_NBR
93C56B-I/P
93C56C-E/P
93C56C-I/P
93C56-E/P
93C66A-E/P
93C66A-I/P
93C66B-E/P
93C66B-E/PRVA
93C66B-I/P
93C66C-E/P
93C66C-I/P
93C66-E/P
93C76A-E/P
93C76A-I/P
93C76B-E/P
93C76B-I/P
93C76C-E/P
93C76C-I/P
93C76-E/P
93C86A-E/P
93C86A-I/P
93C86B-E/P
93C86B-I/P
93C86C-E/P
93C86C-I/P
93C86-E/P
93LC46/P
93LC46A/P
93LC46A/PRVA
93LC46A-E/P
93LC46A-I/P
93LC46A-I/PROCRVA
93LC46B/P
93LC46B/PRVA
93LC46B-E/P
93LC46B-I/P
93LC46B-I/PROCRVA
93LC46B-I/PRVA
93LC46C-E/P
93LC46C-I/P
93LC46-I/P
93LC56/P
93LC56A/P
93LC56A/PRVA



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PCN_JAON-07YGZF687
CATALOG_PART_NBR
93LC56A-E/P
93LC56A-I/P
93LC56A-I/PRVA
93LC56B/P
93LC56B/PRVA
93LC56B-E/P
93LC56B-I/P
93LC56B-I/PRVA
93LC56C-E/P
93LC56C-I/P
93LC56-I/P
93LC66/P
93LC66A/P
93LC66A/PRVA
93LC66A-E/P
93LC66A-I/P
93LC66A-I/PE31
93LC66A-I/PRVA
93LC66B/P
93LC66B/PROCRVA
93LC66B/PRVA
93LC66B-E/P
93LC66B-I/P
93LC66B-I/PROCRVA
93LC66B-I/PRVA
93LC66C-E/P
93LC66C-I/P
93LC66-I/P
93LC76/P
93LC76A-E/P
93LC76A-I/P
93LC76B-E/P
93LC76B-I/P
93LC76C-E/P
93LC76C-I/P
93LC76-I/P
93LC86/P
93LC86A-E/P
93LC86A-I/P
93LC86B-E/P
93LC86B-I/P
93LC86C-E/P
93LC86C-I/P
93LC86-I/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-07YGZF687
CATALOG_PART_NBR
HCS101/P
HCS101-I/P
HCS200/P
HCS200-I/P
HCS201/P
HCS201-I/P
HCS300/P
HCS300-I/P
HCS301/P
HCS301-I/P
HCS320/P
HCS320-I/P
HCS360/P
HCS360-I/P
HCS360-I/P036
HCS361/P
HCS361-I/P
HCS362-I/P
HCS365/P
HCS365-I/P
HCS410/P
HCS410-I/P
HCS500/P
HCS500-I/P
MCP1403-E/P
MCP1404-E/P
MCP1405-E/P
MCP1406-E/P
MCP1407-E/P
MCP14E10-E/P
MCP14E11-E/P
MCP14E3-E/P
MCP14E4-E/P
MCP14E5-E/P
MCP14E6-E/P
MCP14E7-E/P
MCP14E8-E/P
MCP14E9-E/P
MCP1525-I/P
MCP1541-I/P
MCP2122-E/P
MCP3001-I/P
MCP3002-I/P
MCP3201-BI/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-07YGZF687
CATALOG_PART_NBR
MCP3201-CI/P
MCP3202-BI/P
MCP3202-CI/P
MCP3221A5/P
MCP3221A5-I/P
MCP3301-BI/P
MCP3301-CI/P
MCP41010-E/P
MCP41010-I/P
MCP41050-E/P
MCP41050-I/P
MCP41100-E/P
MCP41100-I/P
MCP4131-103E/P
MCP4131-104E/P
MCP4131-502E/P
MCP4131-503E/P
MCP4132-103E/P
MCP4132-104E/P
MCP4132-502E/P
MCP4132-503E/P
MCP4141-103E/P
MCP4141-104E/P
MCP4141-502E/P
MCP4141-503E/P
MCP4142-103E/P
MCP4142-104E/P
MCP4142-502E/P
MCP4142-503E/P
MCP4151-103E/P
MCP4151-104E/P
MCP4151-502E/P
MCP4151-503E/P
MCP4152-103E/P
MCP4152-104E/P
MCP4152-502E/P
MCP4152-503E/P
MCP4161-103E/P
MCP4161-104E/P
MCP4161-502E/P
MCP4161-503E/P
MCP4162-103E/P
MCP4162-104E/P
MCP4162-502E/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-07YGZF687
CATALOG_PART_NBR
MCP4162-503E/P
MCP4801-E/P
MCP4802-E/P
MCP4811-E/P
MCP4812-E/P
MCP4821-E/P
MCP4822-E/P
MCP4901-E/P
MCP4911-E/P
MCP4921-E/P
MCP6002-E/P
MCP6002-I/P
MCP601-E/P
MCP601-I/P
MCP6021-E/P
MCP6021-I/P
MCP6022-E/P
MCP6022-I/P
MCP6023-E/P
MCP6023-I/P
MCP602-E/P
MCP602-I/P
MCP6031-E/P
MCP6031-E/PAAA
MCP6032-E/P
MCP6032-E/PAAA
MCP603-E/P
MCP603-I/P
MCP603-I/PBAA
MCP6041-E/P
MCP6041-I/P
MCP6041-I/PAAA
MCP6042-E/P
MCP6042-I/P
MCP6042-I/PAAA
MCP6043-E/P
MCP6043-I/P
MCP606-I/P
MCP607-I/P
MCP608-I/P
MCP6141-E/P
MCP6141-I/P
MCP6142-E/P
MCP6142-I/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-07YGZF687
CATALOG_PART_NBR
MCP6143-E/P
MCP6143-I/P
MCP616-I/P
MCP617-I/P
MCP618-I/P
MCP6231-E/P
MCP6232-E/P
MCP6241-E/P
MCP6242-E/P
MCP6271-E/P
MCP6272-E/P
MCP6273-E/P
MCP6275-E/P
MCP6281-E/P
MCP6282-E/P
MCP6283-E/P
MCP6285-E/P
MCP6291-E/P
MCP6292-E/P
MCP6293-E/P
MCP6295-E/P
MCP6541-E/P
MCP6541-I/P
MCP6542-E/P
MCP6542-I/P
MCP6543-E/P
MCP6543-I/P
MCP6546-E/P
MCP6546-I/P
MCP6547-E/P
MCP6547-I/P
MCP6548-E/P
MCP6548-I/P
MCP6S21-I/P
MCP6S22-I/P
MCP6S91-E/P
MCP6S92-E/P
MCV08A-I/P
PIC10F200-E/P
PIC10F200-I/P
PIC10F202-E/P
PIC10F202-I/P
PIC10F202-I/P074
PIC10F204-E/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-07YGZF687
CATALOG_PART_NBR
PIC10F204-I/P
PIC10F204-I/P030
PIC10F206-E/P
PIC10F206-I/P
PIC10F206-I/P046
PIC10F220-E/P
PIC10F220-I/P
PIC10F222-E/P
PIC10F222-I/P
PIC10F320-E/P
PIC10F320-I/P
PIC10F322-E/P
PIC10F322-I/P
PIC10LF320-E/P
PIC10LF320-I/P
PIC10LF322-E/P
PIC10LF322-I/P
PIC12C508-04/P
PIC12C508-04E/P
PIC12C508-04I/P
PIC12C508A-04/P
PIC12C508A-04/P072
PIC12C508A-04E/P
PIC12C508A-04I/P
PIC12C508A-04I/P020
PIC12C508A-04I/P227
PIC12C508A-04I/P230
PIC12C509-04/P
PIC12C509-04E/P
PIC12C509-04I/P
PIC12C509A-04/P
PIC12C509A-04E/P
PIC12C509A-04I/P
PIC12C671-04/P
PIC12C671-04E/P
PIC12C671-04I/P
PIC12C671-10/P
PIC12C671-10E/P
PIC12C671-10I/P
PIC12C672-04/P
PIC12C672-04E/P
PIC12C672-04I/P
PIC12C672-10/P
PIC12C672-10E/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-07YGZF687
CATALOG_PART_NBR
PIC12C672-10I/P
PIC12F1501-E/P
PIC12F1501-I/P
PIC12F1571-E/P
PIC12F1571-I/P
PIC12F1572-E/P
PIC12F1572-I/P
PIC12F1612-E/P
PIC12F1612-I/P
PIC12F1822-E/P
PIC12F1822-I/P
PIC12F1822-I/P034
PIC12F1822-I/P038
PIC12F1840-E/P
PIC12F1840-I/P
PIC12F1840-I/PC01
PIC12F508-E/P
PIC12F508-I/P
PIC12F508-I/P058
PIC12F508-I/P059
PIC12F508-I/P060
PIC12F508-I/P072
PIC12F509-E/P
PIC12F509-I/P
PIC12F510-E/P
PIC12F510-I/P
PIC12F510-I/P020
PIC12F510-I/P021
PIC12F510-I/P042
PIC12F510-I/P043
PIC12F510-I/P063
PIC12F519-E/P
PIC12F519-I/P
PIC12F609-E/P
PIC12F609-I/P
PIC12F615-E/P
PIC12F615-I/P
PIC12F617-E/P
PIC12F617-I/P
PIC12F629-C/P
PIC12F629-E/P
PIC12F629-I/P
PIC12F629-I/P231
PIC12F635-E/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-07YGZF687
CATALOG_PART_NBR
PIC12F635-I/P
PIC12F675-C/P
PIC12F675-E/P
PIC12F675-I/P
PIC12F675-I/P103
PIC12F675-I/P115
PIC12F675-I/P127
PIC12F675-I/P141
PIC12F675-I/P163
PIC12F675-I/P189
PIC12F675-I/P192
PIC12F675-I/P193
PIC12F675-I/P198
PIC12F683-E/P
PIC12F683-I/P
PIC12F683-I/P021
PIC12F683-I/P047
PIC12F683-I/P064
PIC12F683-I/P065
PIC12F683-I/P067
PIC12F683-I/P068
PIC12F683-I/P069
PIC12F683-I/P074
PIC12F683-I/P078
PIC12F752-E/P
PIC12F752-I/P
PIC12HV609-E/P
PIC12HV609-I/P
PIC12HV615-E/P
PIC12HV615-I/P
PIC12HV752-E/P
PIC12HV752-I/P
PIC12LC508A-04/P
PIC12LC509A-04/P
PIC12LC671-04/P
PIC12LC671-04I/P
PIC12LC672-04I/P
PIC12LF1501-E/P
PIC12LF1501-I/P
PIC12LF1552-E/P
PIC12LF1552-I/P
PIC12LF1571-E/P
PIC12LF1571-I/P
PIC12LF1572-E/P



JAON-07YGZF687 - CCB 1833 Final Notice: Qualification of CuPdAu bond wire in selected products of different wafer technologies available in 8L PDIP package at MMT assembly site

Affected Catalog Part Numbers (CPN)

PCN_JAON-07YGZF687
CATALOG_PART_NBR
PIC12LF1572-I/P
PIC12LF1612-E/P
PIC12LF1612-I/P
PIC12LF1822-E/P
PIC12LF1822-I/P
PIC12LF1840-E/P
PIC12LF1840-I/P
TC1044SCPA
TC1044SEPA
TC1232CPA
TC1232EPA
TC1410CPA
TC1410EPA
TC1410NCPA
TC1410NEPA
TC1411CPA
TC1411EPA
TC1411NCPA
TC1411NEPA
TC1411NVPA
TC1411VPA
TC1412CPA
TC1412EPA
TC1412NCPA
TC1412NEPA
TC1413CPA
TC1413EPA
TC1413NCPA
TC1413NEPA
TC1426CPA
TC1427CPA
TC1427EPA
TC1427VPA
TC1428CPA
TC1428VPA
TC2185-2.8VPA
TC2185-5.0VPA
TC426CPA
TC426EPA
TC427CPA
TC427EPA
TC427VPA
TC428CPA
TC428CPAROC

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Affected Catalog Part Numbers (CPN)

PCN_JAON-07YGZF687
CATALOG_PART_NBR
TC428EPA
TC429CPA
TC429EPA
TC4403CPA
TC4403EPA
TC4404CPA
TC4404EPA
TC4405CPA
TC4405EPA
TC4420CPA
TC4420EPA
TC4420VPA
TC4421AVPA
TC4421CPA
TC4421EPA
TC4421VPA
TC4422AVPA
TC4422CPA
TC4422EPA
TC4422VPA
TC4423AVPA
TC4423CPA
TC4423EPA
TC4423VPA
TC4424AVPA
TC4424CPA
TC4424EPA
TC4424VPA
TC4425AVPA
TC4425CPA
TC4425EPA
TC4425VPA
TC4426ACPA
TC4426AEPA
TC4426AVPA
TC4426CPA
TC4426EPA
TC4426VPA
TC4427ACPA
TC4427ACPAAAA
TC4427AEPA
TC4427AVPA
TC4427CPA
TC4427EPA

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Affected Catalog Part Numbers (CPN)

PCN_JAON-07YGZF687
CATALOG_PART_NBR
TC4427VPA
TC4428ACPA
TC4428AEPA
TC4428AVPA
TC4428CPA
TC4428EPA
TC4428VPA
TC4429CPA
TC4429EPA
TC4429VPA
TC4431CPA
TC4431EPA
TC4431VPA
TC4432CPA
TC4432EPA
TC4432VPA
TC4451VPA
TC4452VPA
TC4626CPA
TC4626EPA
TC4627CPA
TC4627EPA
TC620CCPA
TC620CEPA
TC620HCPA
TC620HEPA
TC621CCPA
TC621CEPA
TC621HCPA
TC621HEPA
TC622CPA
TC622EPA
TC622VPA
TC623CCPA
TC623CEPA
TC624CPA
TC624EPA
TC624VPA
TC682CPA
TC682EPA
TC7650CPA
TC7652CPA
TC7660CPA
TC7660EPA

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Affected Catalog Part Numbers (CPN)

PCN_JAON-07YGZF687
CATALOG_PART_NBR
TC7660HCPA
TC7660HEPA
TC7660SCPA
TC7660SEPA
TC7662ACPA
TC7662AEPa
TC7662BCPA
TC7662BEPA
TC913ACPA
TC913BCPA
TC962CPA
TC962EPA



**MICROCHIP**

**QUALIFICATION REPORT**  
RELIABILITY LABORATORY

**PCN #: JAON-07YGZF687**

**Date**  
**March 18, 2016**

**Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 8L PDIP package at MMT assembly site. The selected products of the 40K, 42K, 77K, 90K, 120K, 121K, 150K and 160K wafer technologies available in 8L PDIP package MMT assembly site will qualify by similarity.**

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## MICROCHIP PACKAGE QUALIFICATION REPORT

<b>Purpose</b>	Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 8L PDIP package at MMT assembly site. The selected products of the 40K, 42K, 77K, 90K, 120K, 121K, 150K and 160K wafer technologies available in 8L PDIP package MMT assembly site will qualify by similarity.
<b>CN</b>	BC160053
<b>QUAL ID</b>	Q16050
<b>MP CODE</b>	LEBD24C4XB04
<b>Part No.</b>	PIC12F1822-E/P
<b>Bonding No.</b>	BDM-000982 Rev. A
<b>CCB No.</b>	1833
<b><u>Package</u></b>	
<b>Type</b>	8L PDIP
<b>Package size</b>	300 mils
<b>Die thickness</b>	15 mils
<b>Die size</b>	61.0 x 92.0 mils
<b><u>Lead Frame</u></b>	
<b>Paddle size</b>	100 x 140 mils
<b>Material</b>	CDA194
<b>Surface</b>	Ag Spot Plated
<b>Process</b>	Stamped
<b>Lead Lock</b>	No
<b>Part Number</b>	10100823
<b>Treatment</b>	None
<b><u>Die attach material</u></b>	
<b>Epoxy</b>	CRM-1064L
<b>Wire</b>	CuPdAu wire
<b>Mold Compound</b>	GE800
<b>Plating Composition</b>	Matte Tin



## MICROCHIP PACKAGE QUALIFICATION REPORT

### Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-164300513.000	GRSM416242643.210	1603QSD
MMT-164300804.000	GRSM416242643.210	1603TRW
MMT-164300862.000	GRSM416242643.210	1603TYK

**Result**       Pass       Fail       \_\_\_\_\_

8L PDIP (.300") assembled by MMT (ALPH) pass reliability test per QCI-39000.

Prepared By: Thinnapol Date: March 18, 2016 (Sr. Reliability Engineer)

(Mr. Thinnapol Nakkasun)

Approved By: Som Date: March 18, 2016 (Reliability Manager)

(Mr. Somnuek Thongprasert)

## PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
<b>Electrical Test</b>	<b>Electrical Test:</b> +25°C ,125°C and -40°C System: J750	JESD22- A113	693(0)	693		Good Devices
<b>Temp Cycle</b>	<b>Stress Condition:</b> (Standard) 65°C to +150°C, 500 Cycles System : TABAI ESPEC TSA-70H	JESD22- A104		231		
	<b>Electrical Test:</b> + 125°C System: J750		231(0)	0/231	Pass	77 units / lot
	<b>Bond Strength:</b> Wire Pull (> 3.0 grams) Bond Shear (>20.00 grams)		15 (0)	0/15	Pass	
<b>UNBIASED-HAST</b>	<b>Stress Condition:</b> (Standard) +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22- A118		231		
	<b>Electrical Test:</b> +25°C System: J750		231(0)	0/231	Pass	77 units / lot



## PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
<b>HAST</b>	<b>Stress Condition:</b> (Standard) +130°C/85%RH, 96 hrs. <b>Bias Volt:</b> 5.5 Volts System: HAST 6000X  <b>Electrical Test:</b> +25°C and 125°C System: J750	JESD22- A110	231(0)	231  0/231	Pass	77 units / lot
<b>High Temperature Storage Life</b>	<b>Stress Condition:</b> Bake 175°C, 504 hrs System: SHEL LAB  <b>Electrical Test:</b> + 25°C and 125°C System: J750	JESD22 -A103	45(0)	45  0/45	Pass	45 units
<b>Bond Strength</b>	Wire Pull (> 3.0 grams)	JESD22 -B116	30 (0) Wires	0/30	Pass	
<b>Data Assembly</b>	Bond Shear (>20.00 grams)		30 (0) bonds	0/30	Pass	